

LOW CAPACITANCE STEERING DIODE & TVS ARRAYS

APPLICATIONS

- ✓ Ethernet 10/100 Base T
- ✔ Computer I/O Ports- SCSI, FireWire & USB
- ✓ Set Top Box Protection

IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air 15kv, Contact 8kv
- ✓ 61000-4-4 (EFT): 40A 5/50ns
- ✓ 61000-4-5 (Surge): 24A, 8/20µs Level 2(Line-Gnd) & Level 3(Line-Line)

FEATURES

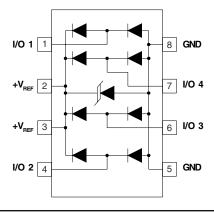
- ✓ 500 Watts Peak Pulse Power Dissipation(t_a = 8/20µs)
- ✓ Unidirectional Configuration
- ✔ Available in 4 Voltage Types: 3.3V to 15V
- ✔ Protects Up to Four (4) I/O Ports
- ✓ ESD Protection > 40 kilovolts
- **✓ LOW CAPACITANCE-15pF**

MECHANICAL CHARACTERISTICS

- ✓ Molded JEDEC SO-8
- ✓ Weight 15 milligrams (Approximate)
- ✓ Flammability Rating UL 94V-0
- ✓ 12mm Tape and Reel Per EIA Standard 481-1-A
- ✔ Device Marking Code & Logo
- ✔ Pin 1 Indicated By Dot on Package

SO-8

CIRCUIT DIAGRAM



1

DEVICE CHARACTERISTICS

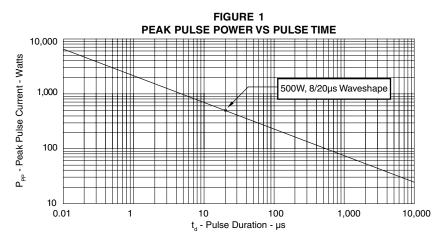
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified							
PARAMETER	SYMBOL	VALUE	UNITS				
Operating Temperature	T_{J}	-55°C to 150°C	°C				
Storage Temperature	T _{STG}	-55°C to 150°C	°C				
Maximum Forward Voltage @ 100 mA (See Note 1)	V _F	1.1	Volts				

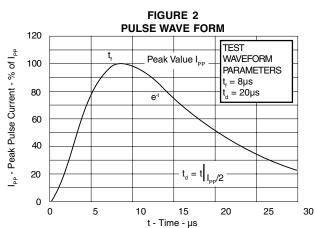
Note 1: Measured between pins 8 or 5 to 1, 2, 3, 4, 6 and 7.

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified							
PART NUMBER (See Note 1)	DEVICE MARKING	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ I _P = 1A V	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT @ V _{WM} I _D	MAXIMUM CAPACITANCE (See Note 2) (See Figure 5) OV @ 1 MHz C
		VOLTS		VOLTS	V _C @ I _{PP}	μΑ	pF
PSRDA3.3-4 PSRDA05-4 PSRDA12-4 PSRDA15-4	PRA PRB PRD PRE	3.3 5.0 12.0 15.0	4.0 6.0 13.3 16.7	6.5 9.8 19.0 24.0	10.9V @ 43.0A 13.5V @ 42.0A 25.9V @ 21.0A 30.0V @ 17.0A	125 20 1 1	15 15 15 15

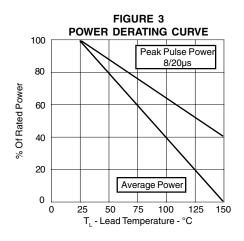
Note 1: Spice model and parameters for this series are available on the ProTek Devices web site: www.protekdevices.com.

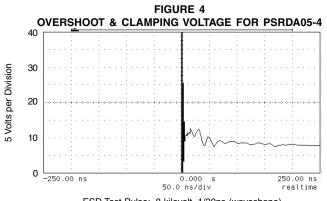
Note 2: Capacitance measured at $V_{WM} = V_{CC}$ connected between I/O pins to pin 8 and 5 (Gnd). $V_R = V_{WM}$ @ 1MHz. As shown in Figure 5, REF1 is connected to ground, REF2 is connected to + V_{CC} , and input applies to $V_{CC} = 5V$, $V_{sign} = mV$, F = 1 MHz.





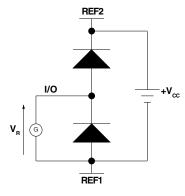
GRAPHS

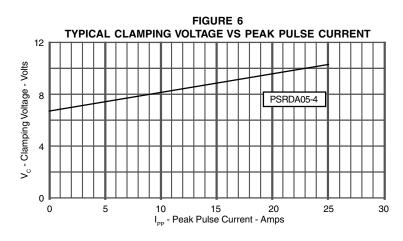


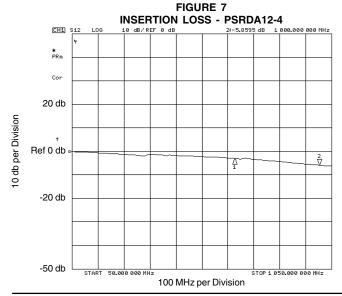


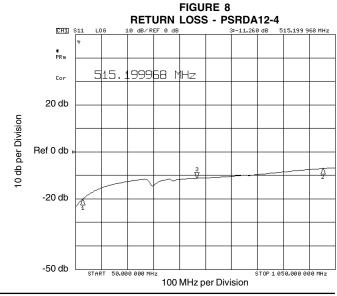
ESD Test Pulse: 8 kilovolt, 1/30ns (waveshape)

FIGURE 5 INPUT CAPACITANCE CIRCUIT









APPLICATION NOTE

The PSRDAxx-4 Series are low capacitance, unidirectional TVS arrays that are designed to protect I/O or high speed data lines from the damaging effects of ESD or EFT. This product series has a surge capability of 500 Watts P_{PP} per line for an 8/20 μ s waveshape and offers ESD protection > 40kv.

DIFFERENTIAL MODE CONFIGURATION (Figure 1)

Ideal for use in USB applications, the PSRDAxx-4 Series provides up to four (4) lines of protection in a differential mode configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- ✔ Pins 1, 4, 6 and 7 are connected to the data lines.
- Pins 5 and 8 are connected to ground.
- ✓ Pins 2 and 3 are connected to the databus.

DIFFERENTIAL MODE CONFIGURATION (Figure 2)

The PSRDAxx-4 Series also provides up to four (4) lines of protection in a differential mode configuration as depicted in Figure 2 for T1/E1 applications.

Circuit connectivity is as follows:

- Pins 1, 4, 6 and 7 are connected to the data lines.
- ✔ Pins 5 and 8 are connected to ground.
- ✓ Pins 2 and 3 are connected to the databus.

CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible.
 For multilayer PCBs, use ground vias.

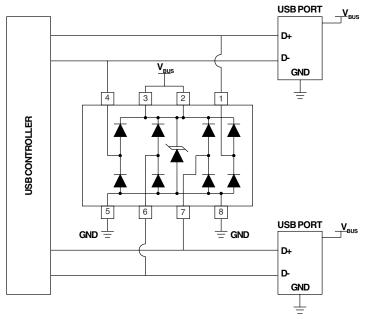


Figure 1. Typical Differential-Mode USB Protection

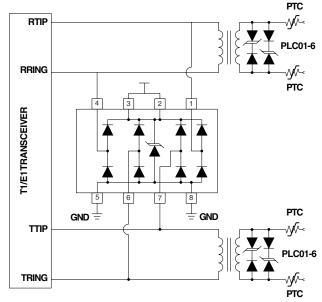
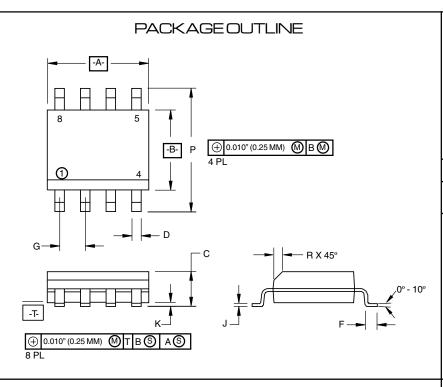


Figure 2. Typical Differential-Mode T1/E1 Protection

PACKAGE OUTLINE & DIMENSIONS



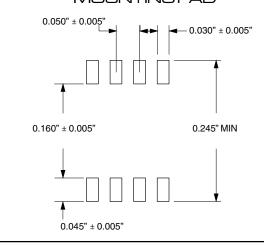
SO-8



PACKAGE DIMENSIONS

	MILLIME	ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.196	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.250	0.016	0.049	
G	1.27 BSC	1.27 BSC	0.05 BSC	0.05 BSC	
J	0.18	0.25	0.007	0.009	
K	0.10	0.25	0.004	0.008	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

MOUNTINGPAD



NOTES

- 1. T = Seating Plane and Datum Surface.
- 2. Dimensions "A" and "B" are Datum.
- 3. Dimensions "A" and "B" do not include mold protrusion.
- Maximum mold protrusion is 0.015" (0.380 mm) per side.
- 5. Dimensioning and tolerances per ANSI Y14.5M, 1982.
- 6. Dimensions are exclusive of mold flash and metal burrs

06009 Rev 1 -11/01

TAPE & REEL PACKAGING:

Surface mount product is taped and reeled in accordance with EIA-481, reel quantites and sizes are as follows:

7 Inch Reel - 1,000 pieces per reel; 13 Inch Reel - 2,500 pieces per reel

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